

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory |   | User Part Number BZX585-C16 Part Description  |                                   |           |            |           |  |                           |  |               |       |  |  |  |
|---|---|---|-----------------------------------|-----------|------------|-----------|--|---------------------------|--|---------------|-------|--|--|--|
|   |   |   |                                   |           |            |           |  |                           |  | Nexperia DHAM | Zener |  |  |  |
|   |   |   |                                   |           |            |           |  | Assembly reliability labs |  | SMD package   |       |  |  |  |
| Based on AEC-Q101 Test                    |   | Test Conditions   | Duration                          | # Lots    | # Quantity | # Rejects |  |                           |  |               |       |  |  |  |
|   | TEST  |   |                                   |           |            |           |  |                           |  |               |       |  |  |  |
|   | Pre- and Post-Stress                                    |   |                                   |           |            |           |  |                           |  |               |       |  |  |  |
| # E1                                      | Electrical Test   | Tamb = 25 °C  | N/A                               | see below | all parts  | see below |  |                           |  |               |       |  |  |  |
| # A1                                      | <b>PC</b> Preconditioning                               | JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering                         | 24 hours<br>168 hours<br>3 cycles | 810       | 58300      | 0         |  |                           |  |               |       |  |  |  |
| # B1                                      | HTRB<br>High Temperature Reverse<br>Bias                | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet<br>reverse voltage       | 1000 hours                        | 138       | 11040      | 0         |  |                           |  |               |       |  |  |  |
| # B1b                                     | SSOP Steady State Operational                           | MIL-STD-750-1<br>M1038 Method B<br>Tj = Tjmax, Iz = 100% of max. datasheet<br>reverse current       | 1000 hours                        | 20        | 1600       | 0         |  |                           |  |               |       |  |  |  |
| # A4                                      | TC<br>Temperature Cycling                               | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 1000 cycles                       | 170       | 13600      | 0         |  |                           |  |               |       |  |  |  |
| # A3 alt                                  | <b>AC</b><br>Autoclave                                  | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)                          | 96 hours                          | 170       | 13600      | 0         |  |                           |  |               |       |  |  |  |
| # A2 alt                                  | H3TRB<br>High Humidity High<br>Temperature Reverse Bias | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1]}$                     | 1000 hours                        | 170       | 13600      | 0         |  |                           |  |               |       |  |  |  |
| # A5                                      | IOL Intermittent Operating Life                         | MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj = 100$ °C for 15000 cycles | 1000 hours                        | 170       | 13600      | 0         |  |                           |  |               |       |  |  |  |
| # C8                                      | RSH<br>Resistance to Solder Heat                        | JESD22-A111<br>260 °C ± 5 °C  | 10 s                              | 130       | 3900       | 0         |  |                           |  |               |       |  |  |  |
| # C10                                     | SD<br>Solderability                                     | J-STD-002   |                                   | 363       | 3630       | 0         |  |                           |  |               |       |  |  |  |

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia  |            |          |         |                    |            |
| DHAM      | Zener      | 11040    | 0       | 0.38               | 2.60E+09   |

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